



P/N: HY160808 SRF07

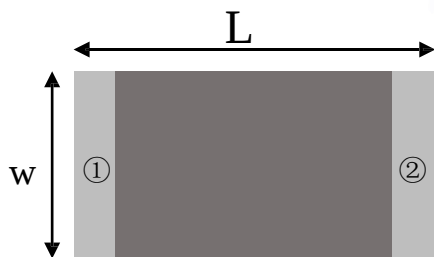
Features

- 1. Surface mounted devices with a small dimension of $1.6 \times 0.8 \times 0.8$ mm meet future miniaturization trend.
- 2. Embedded and LTCC (low temperature co-fired ceramic) technology is able to integrate with system design as well as beautifying the housing of final product.
- 3. High stability and low tolerance.

Applications

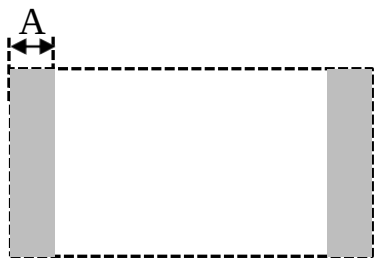
- 1. Bluetooth
- 2. Wireless LAN
- 3. ISM band 2.4GHz wireless applications

Dimensions (Unit: mm)

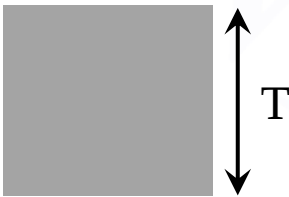


(Top View)

Number	Terminal Name
①	INPUT
②	NC



(Bottom View)



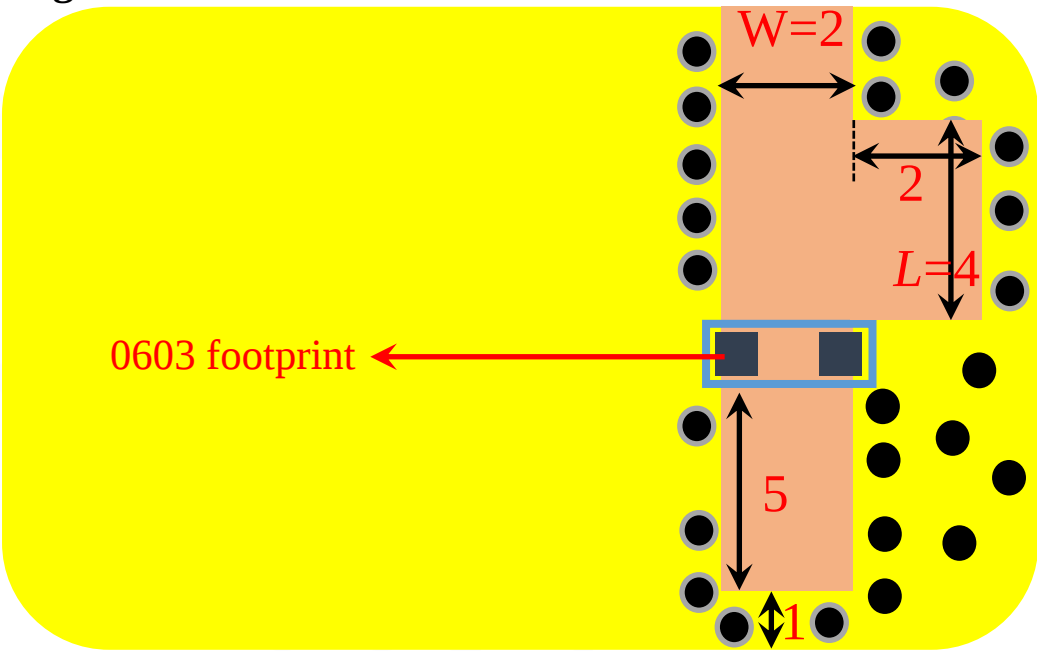
(Side View)

Symbols	L	W	T	A
Dimensions	1.60 ± 0.20	0.80 ± 0.20	0.80 ± 0.20	0.30 ± 0.10

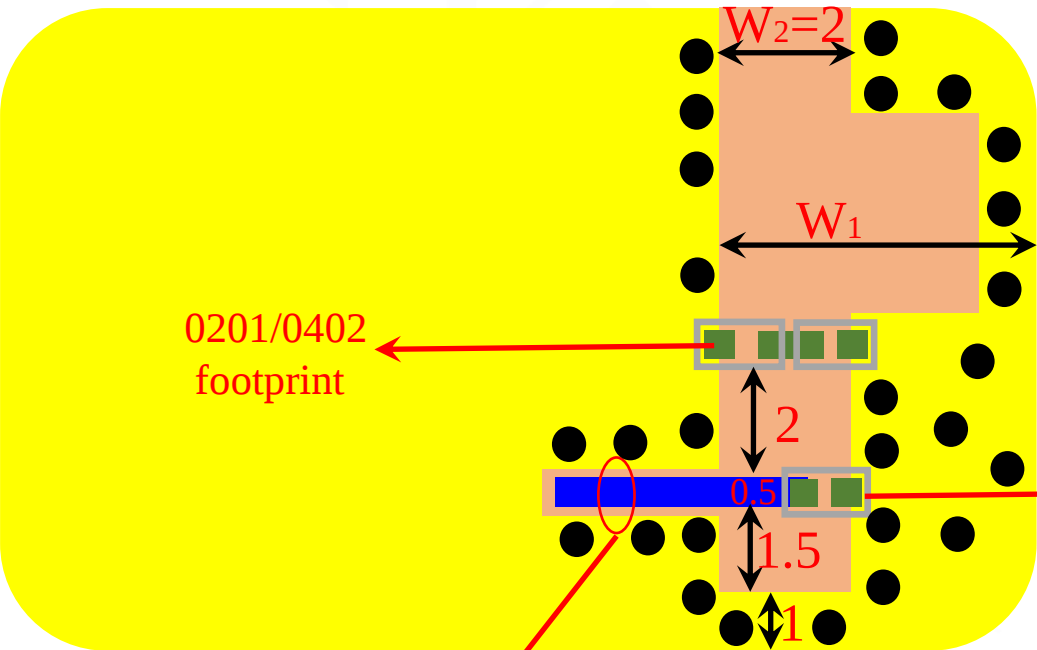


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Matching Circuits



Unit:mm





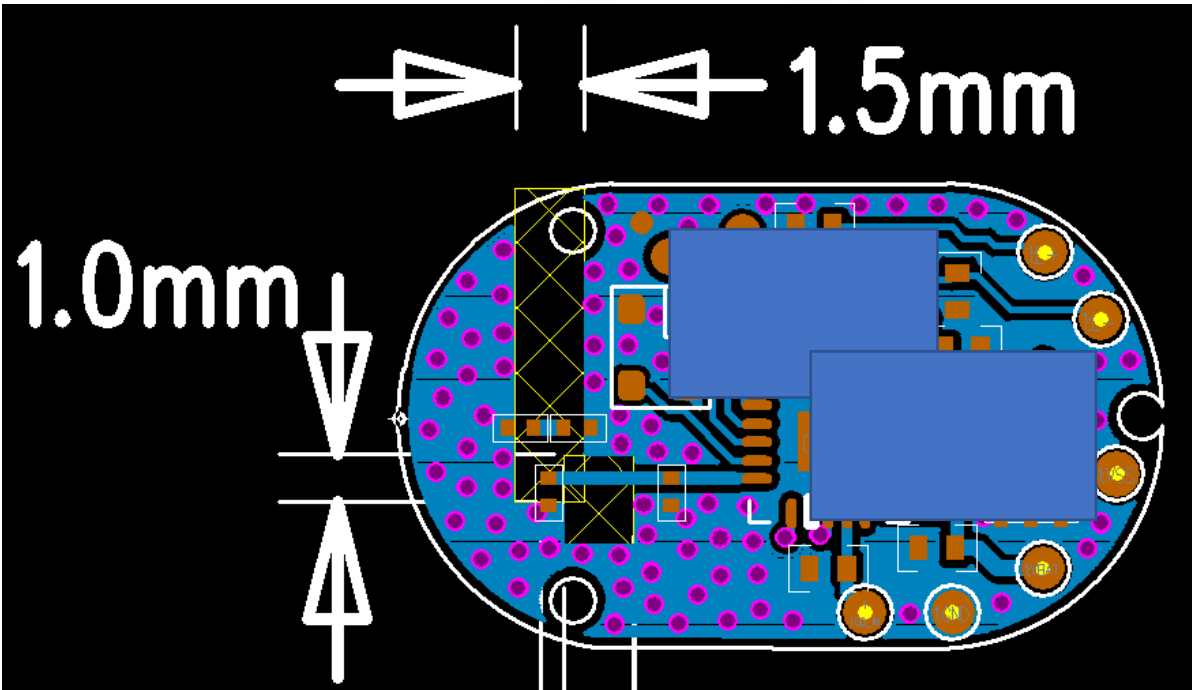
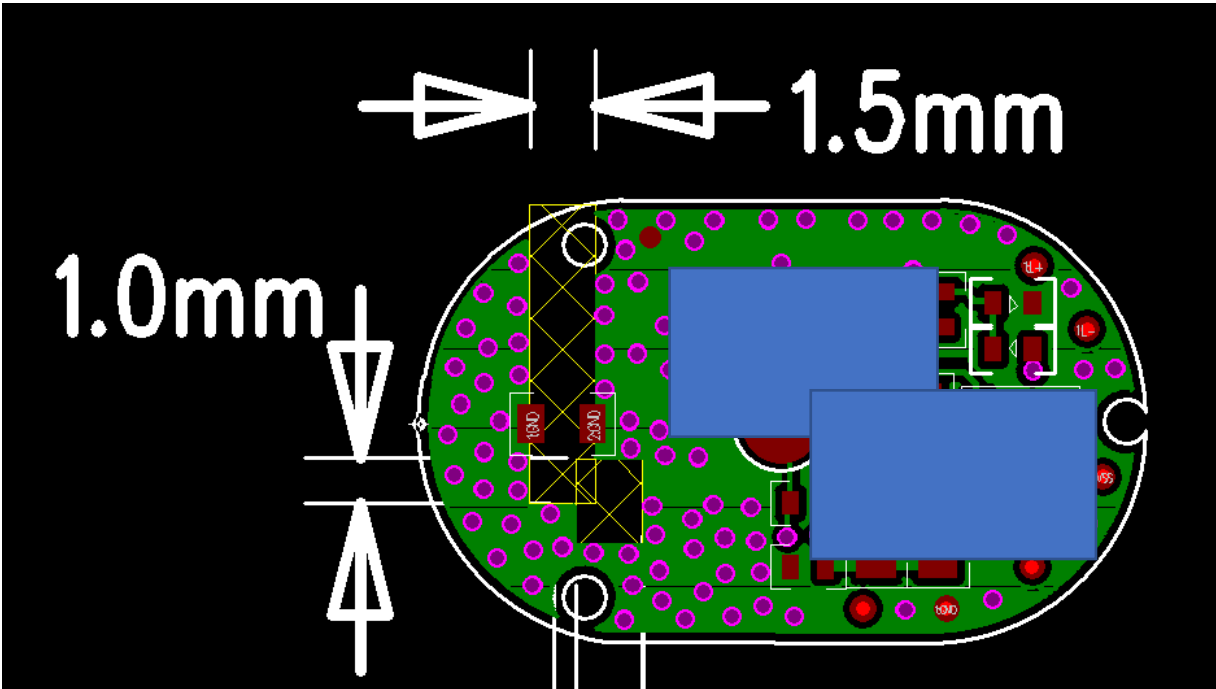
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Application example-2



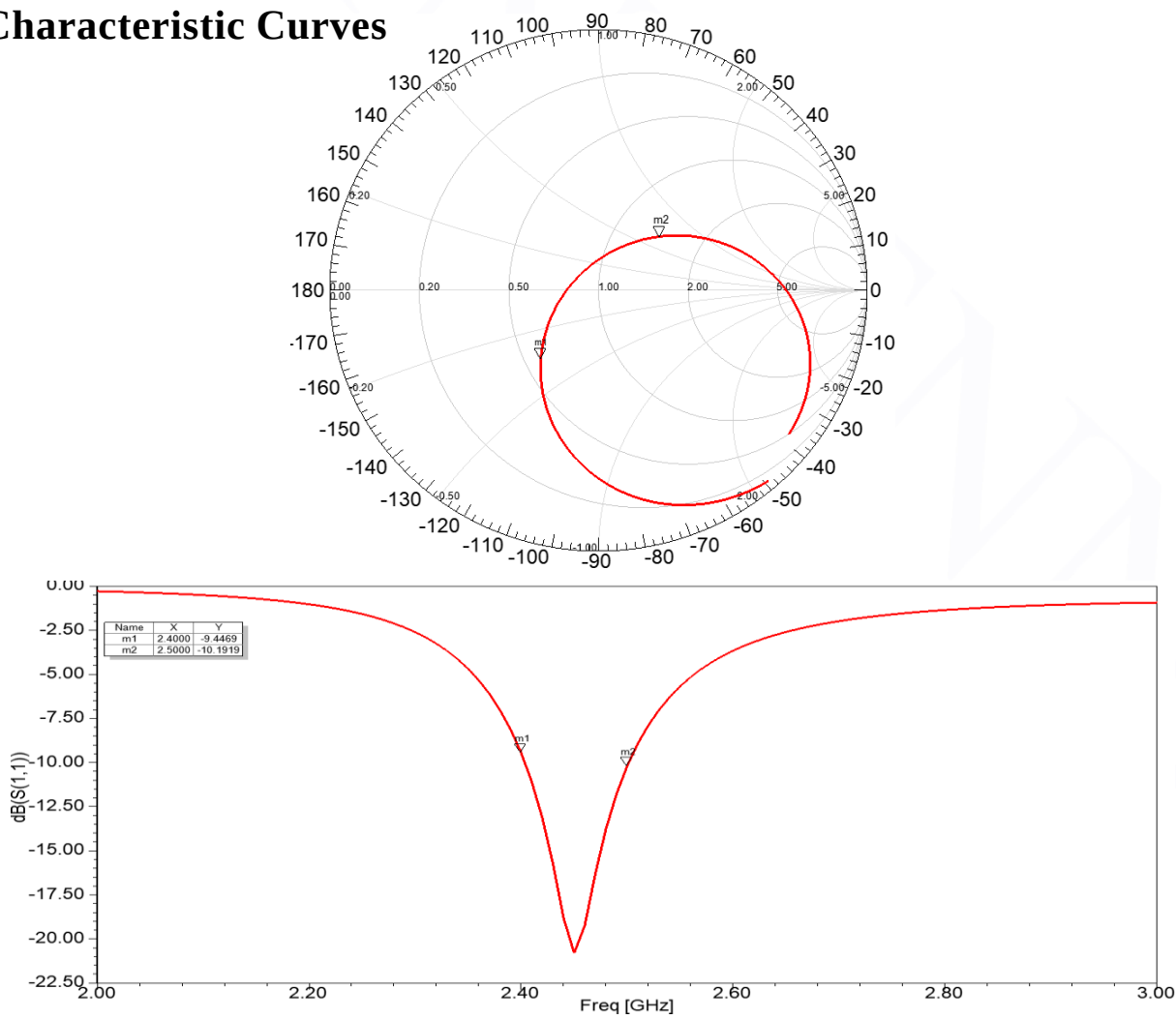


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Electrical Characteristics

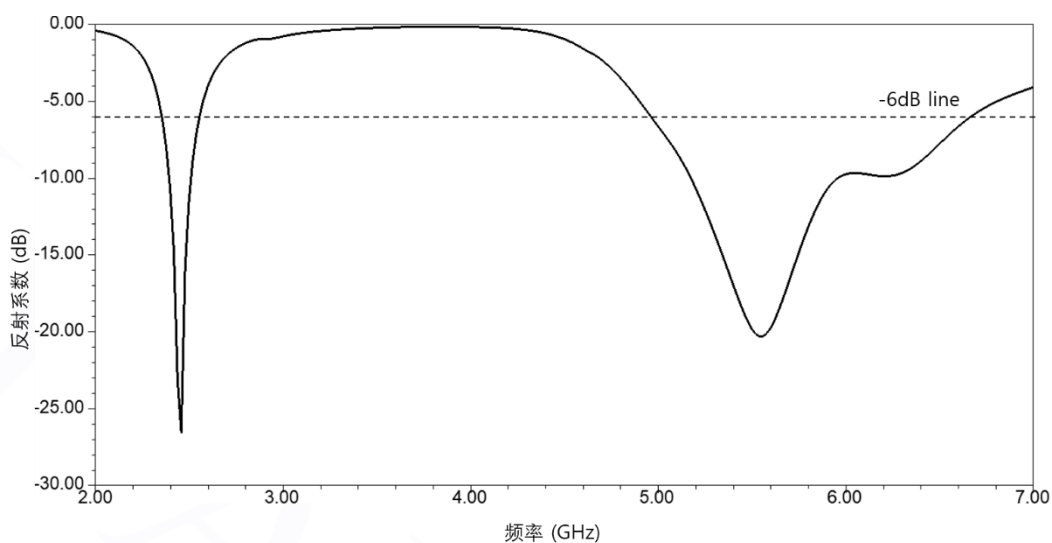
	Feature	Specification
1	Central frequency	2.45GHz
2	Bandwidth	100MHz
3	Peak gain	3dBi
4	VSWR	2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic Curves

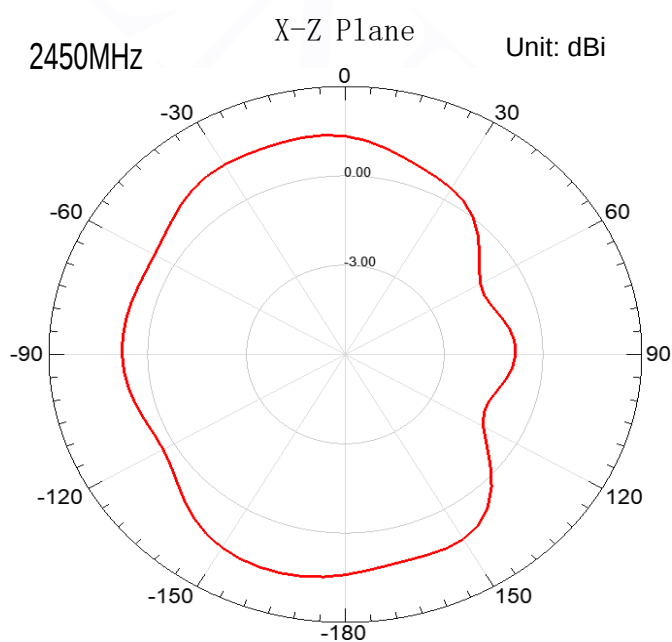
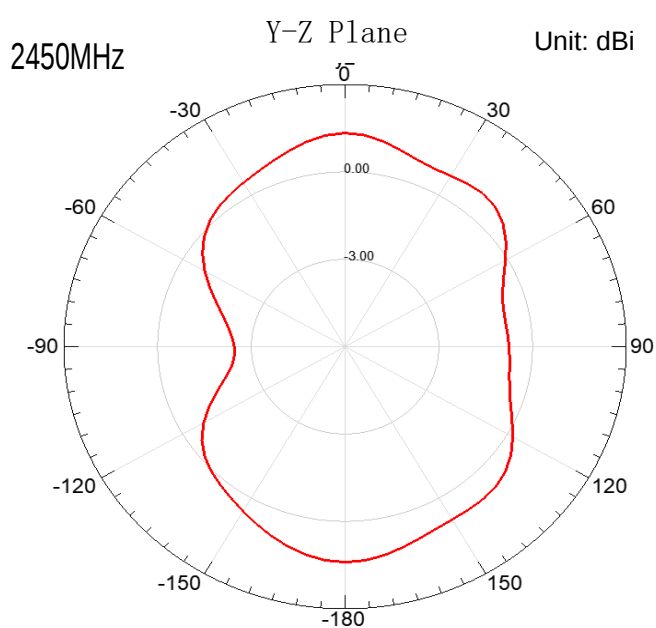
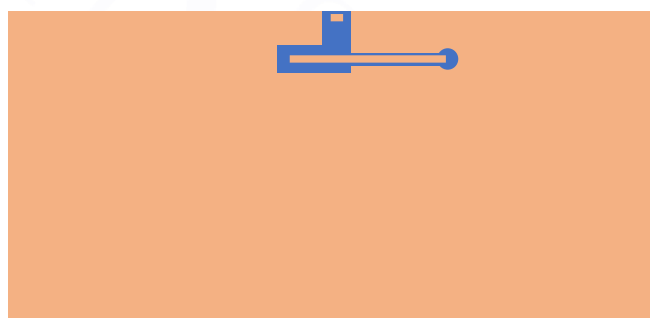
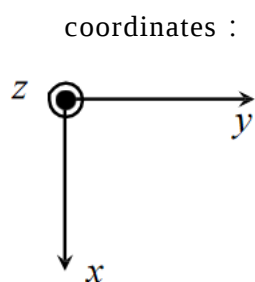




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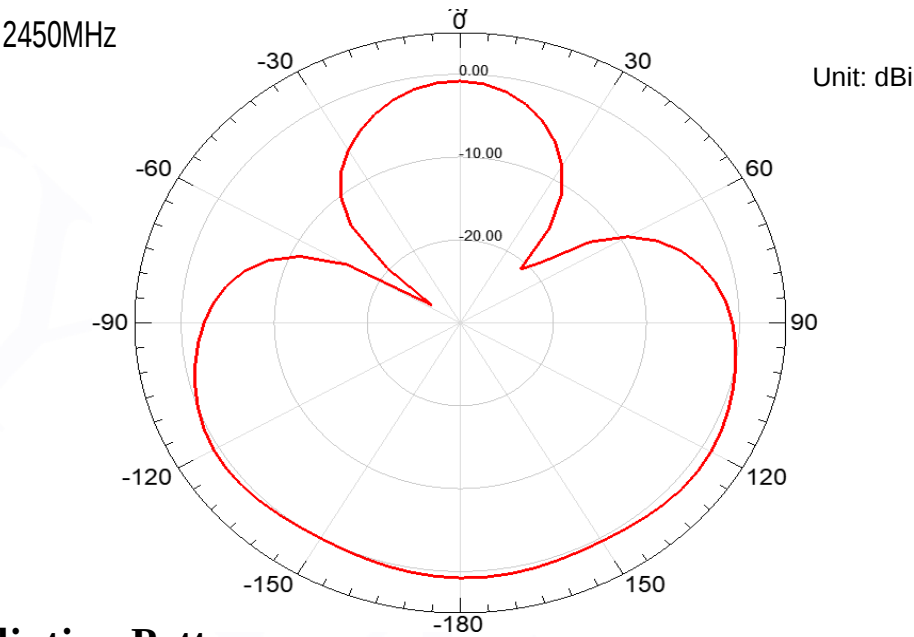


Radiation Pattern

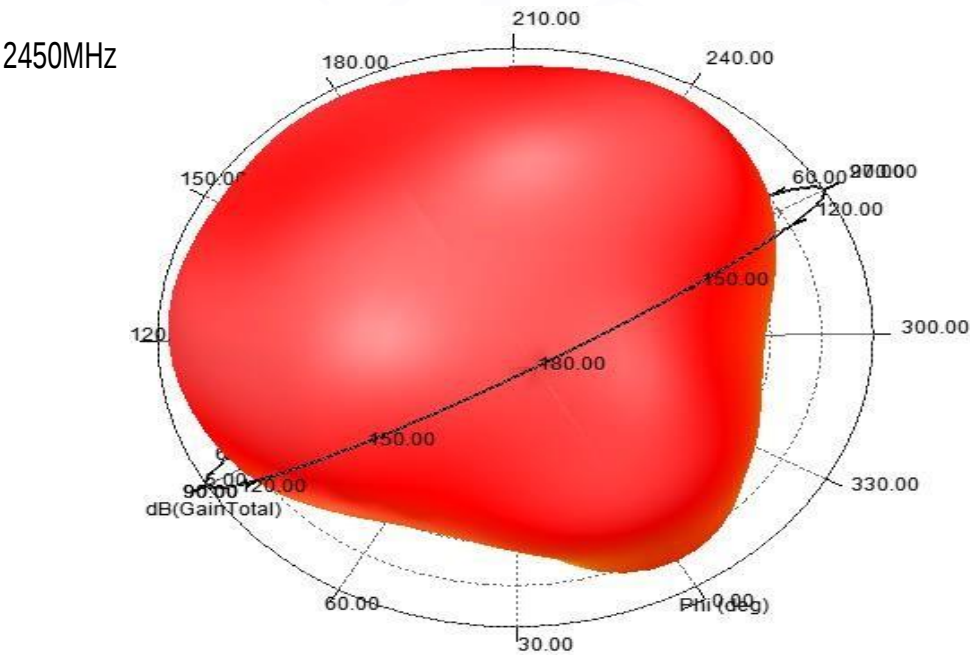




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3D Radiation Pattern



Frequency	2450MHz
Avg. gain	-0.85dBi
Peak gain	3.0dBi
Efficiency	82%



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Dependability Test

Test Temperature	25°C ± 3°C
Operating Temperature	-25°C ~ +85°C
Temperature	5 ~ 40°C
Relative Humidity	20 ~ 70%

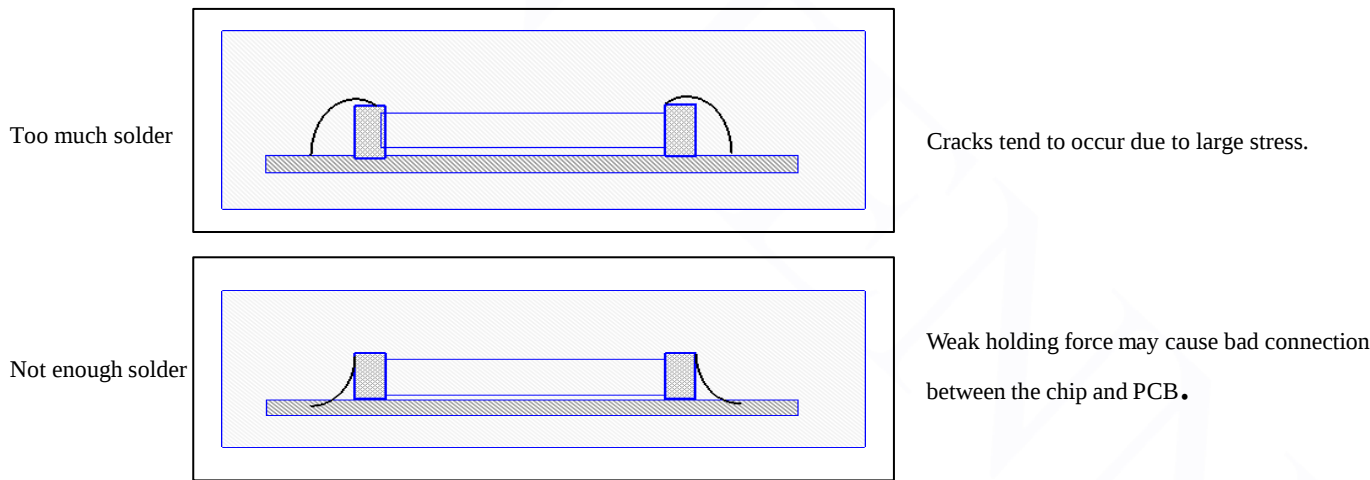
Moisture Proof

Temperature: 40 ± 2°C Humidity: 90 ~ 95%RH
Duration: 500h
Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)

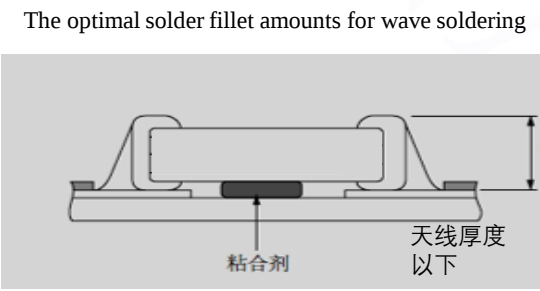
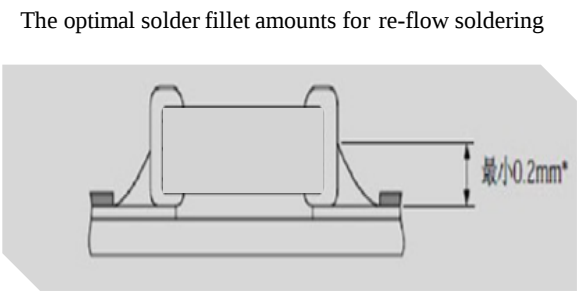
Solderability

At least 95% of the terminal electrode is covered by new solder.
Preheating conditions: 80 to 120°C; 10 ~ 30s.
Solder Temperature: 235 ± 5°C Duration: 2 ± 0.5s, Solder Temperature: 245 ± 5°C Duration: 2 ± 0.5s

Optimum Solder Amount for Reflow Soldering



Recommended Soldering Amounts





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Temperature Cycle Test

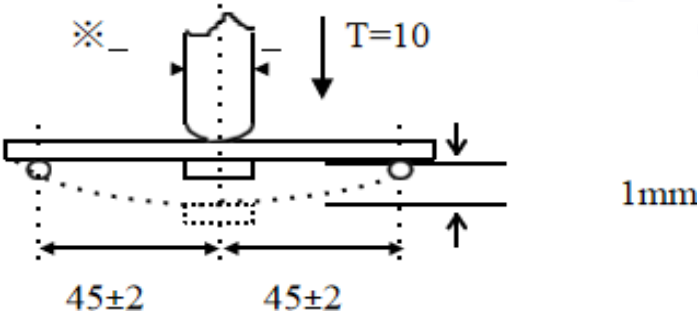
10±1S Applied Force: 5N Duration: 10±1S
Preheating conditions: up-category temperature, 1h
Recovery time: 24±1h
Initial Measurement
Cycling Times: 5 times, 1 cycle, 4 steps:

阶段	温度 (℃)	时间 (分钟)
第 1 步	下限温度(NPO/X7R/X7S/X6S/X5R:-55 Y5V:-25 Z5U:+10)	30
第 2 步	常温 (+20)	2~3
第 3 步	上限温度(NPO/X7R/X7S: +125 Y5V/Z5U/X5R:-85 X6S:-105)	30
第 4 步	常温 (+20)	2~3

Resistance to Soldering Heat

Preheating 80 to 120°C; 10~30s.Solder Temperature: 235±5°C; Duration:2±0.5s; Solder Temperature: 245±5°C
Duration: 2±0.5s; Preheating100 to 200°C; 10±2min.
Solder Temperature: 265±5°C; Duration: 10±1s
Clean the capacitor with solvent and examine it with a 10X(min.) microscope.
Recovery Time: 24±2h
Recovery condition: Room temperature

Resistance to Flexure of Substrate



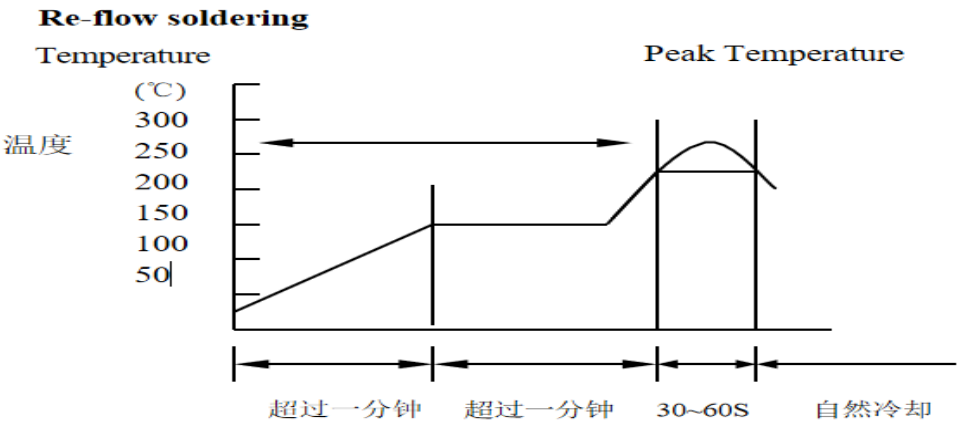
Test Board: Al₂O₃ or PCB Warp: 1mm Speed: 0.5mm/sec.
Unit: mm

The measurement should be made with the board in the bending position.



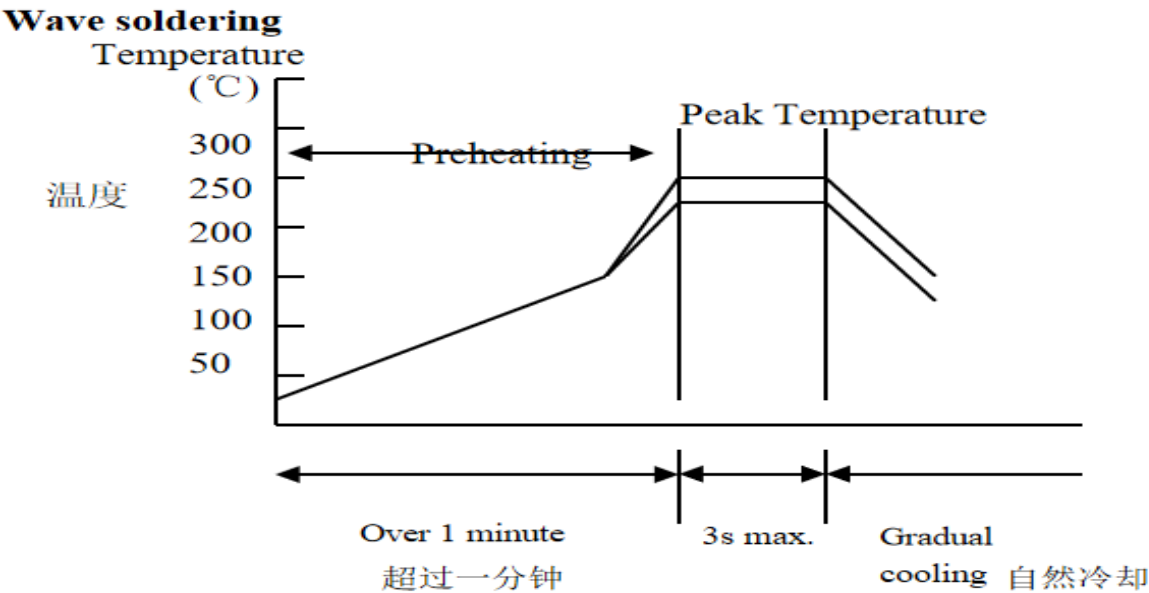
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The temperature profile for soldering



	Pb-Sn 焊接 Pb-Sn soldering	无铅焊接 Lead-free soldering
尖峰温度 Peak temperature	230℃~250℃	240℃~260℃

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \leq 150^{\circ}\text{C}$.

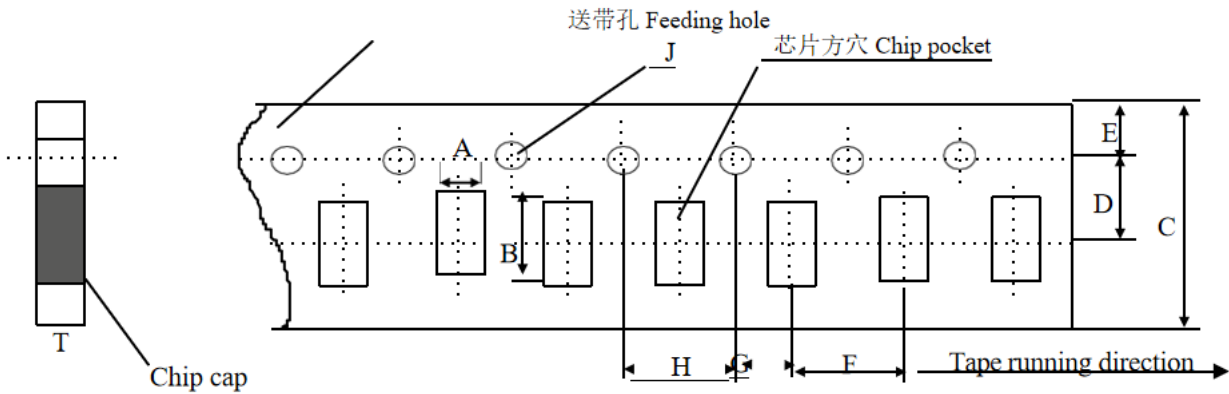


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Dimensions of paper taping

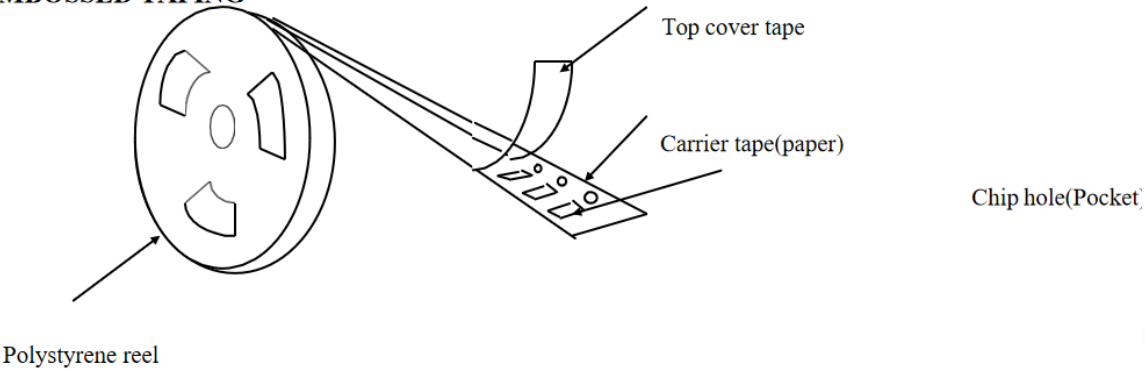


Unit: mm

代号Code 纸带规格 papersize	A	B	C	D*	E	F	G*	H	J	T
尺寸	1.10 ±0.10	1.90 ±0.10	8.00 ±0.10	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max

Reel (4000 pcs/Reel)

EMBOSED TAPING



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition).
Temperature:5~40°C /Relative Humidity:20~70%

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